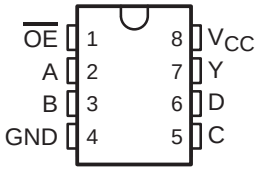
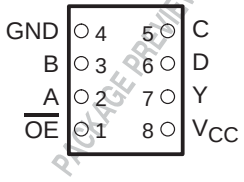
- **Available in the Texas Instruments NanoStar™ and NanoFree™ Packages**
- **Low Static-Power Consumption; I_{CC} = 0.9-μA Max**
- **Low Dynamic-Power Consumption; C_{pd} = 5 pF Typ at 3.3 V**
- **Low Input Capacitance; C_i = 1.5 pF Typ**
- **Low Noise − Overshoot and Undershoot <10% of V_{CC}**
- **Input-Disable Feature Allows Floating Input Conditions**
- **I_{off} Supports Partial-Power-Down Mode Operation**
- **Includes Schmitt-Trigger Inputs**
- **Wide Operating V_{CC} Range of 0.8 V to 3.6 V**
- **Optimized for 3.3-V Operation**
- **3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation**
- **t_{pd} = 7.4 ns Max at 3.3 V**
- **Suitable for Point-to-Point Applications**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Performance Tested Per JESD 22**
  - **2000-V Human-Body Model (A114-B, Class II)**
  - **200-V Machine Model (A115-A)**
  - **1000-V Charged-Device Model (C101)**

DCT OR DCU PACKAGE
(TOP VIEW)



YEP OR YZP PACKAGE
(BOTTOM VIEW)



description/ordering information

The AUP family is TI's premier solution to the industry's low-power needs in battery-powered portable applications. This family ensures a very low static- and dynamic-power consumption across the entire V_{CC} range of 0.8 V to 3.6 V, resulting in an increased battery life. This product also maintains excellent signal integrity (see Figures 1 and 2).

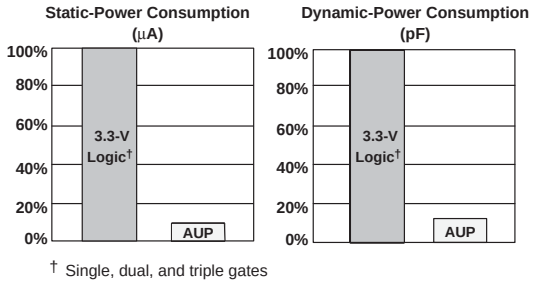


Figure 1. AUP − The Lowest-Power Family

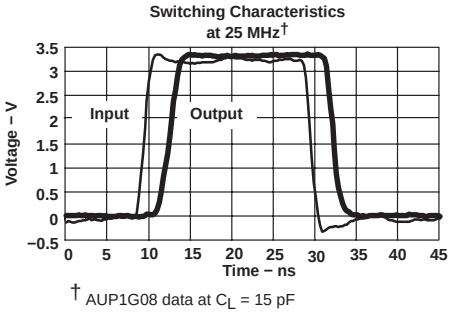


Figure 2. Excellent Signal Integrity

The SN74AUP1G99 features configurable multiple functions with a 3-state output. This device has the input-disable feature, which allows floating input signals. The inputs and output are disabled when the output-enable ($\overline{OE}$) input is high. When $\overline{OE}$ is low, the output state is determined by 16 patterns of 4-bit input. The user can choose the logic functions, such as MUX, AND, OR, NAND, NOR, XOR, XNOR, inverter, and buffer. All inputs can be connected to V_{CC} or GND.

description/ordering information (continued)

This device functions as an independent gate with Schmitt-trigger inputs, which allows for slow input transition and better switching noise immunity at the input.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING‡
−40°C to 85°C	NanoStar™ − WCSP (DSBGA) 0.23-mm Large Bump − YEP	Tape and reel	SN74AUP1G99YEPR	_ _ _HY_
	NanoFree™ − WCSP (DSBGA) 0.23-mm Large Bump − YZP (Pb-free)	Tape and reel	SN74AUP1G99YZPR	
	SSOP − DCT	Tape and reel	SN74AUP1G99DCTR	H99_ _ _
	VSSOP − DCU	Tape and reel	SN74AUP1G99DCUR	H99_

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

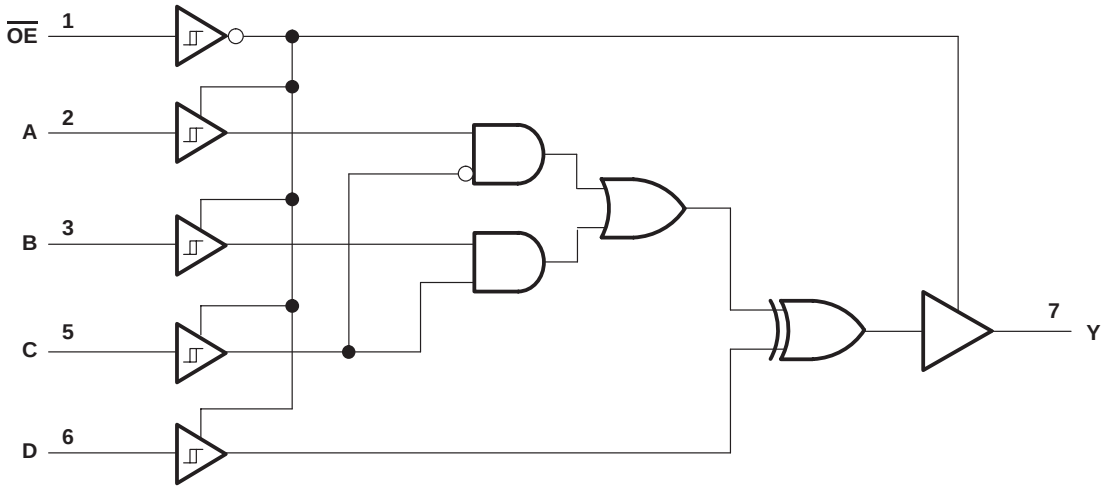
‡ DCT: The actual top-side marking has three additional characters that designate the year, month, and assembly/test site.
DCU: The actual top-side marking has one additional character that designates the assembly/test site.
YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, ● = Pb-free).

FUNCTION TABLE

INPUTS					OUTPUT
$\overline{OE}$	D	C	B	A	Y
L	L	L	L	L	L
L	L	L	L	H	H
L	L	L	H	L	L
L	L	L	H	H	H
L	L	H	L	L	L
L	L	H	L	H	L
L	L	H	H	L	H
L	L	H	H	H	H
L	H	L	L	L	H
L	H	L	L	H	L
L	H	L	H	L	H
L	H	L	H	H	L
L	H	H	L	L	H
L	H	H	L	H	H
L	H	H	H	L	L
L	H	H	H	H	L
H	X†	X†	X†	X†	Z

† Floating inputs allowed.

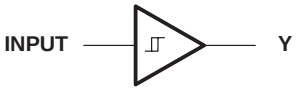
logic diagram (positive logic)



FUNCTION SELECTION TABLE

PRIMARY FUNCTION	COMPLEMENTARY FUNCTION	PAGE
3-state buffer		4
3-state inverter		4
3-state 2-to-1 data selector MUX		5
3-state 2-to-1 data selector MUX, inverted out		5
3-state 2-input AND	3-state 2-input NOR, both inputs inverted	5
3-state 2-input AND, 1 input inverted	3-state 2-input NOR, 1 input inverted	5
3-state 2-input AND, both inputs inverted	3-state 2-input NOR	5
3-state 2-input NAND	3-state 2-input OR, both inputs inverted	6
3-state 2-input NAND, 1 input inverted	3-state 2-input OR, 1 input inverted	6
3-state 2-input NAND, both inputs inverted	3-state 2-input OR	6
3-state 2-input XOR		6
3-state 2-input XNOR	3-state 2-input XOR, 1 input inverted	7

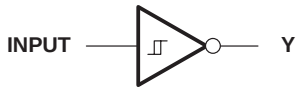
3-STATE BUFFER FUNCTIONS AVAILABLE



FUNCTION	$\overline{OE}$	A	B	C	D
3-state buffer	L	Input	X	L	L
		X	Input	H	L
		L	H	Input	L
		H	L	Input	H
		H	X	L	Input
		X	L	H	Input
		L	L	X	Input

X = H or L

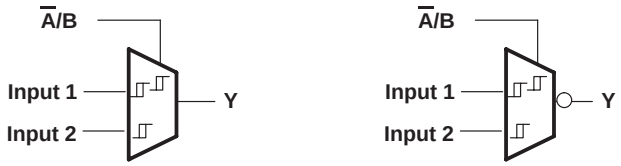
3-STATE INVERTER FUNCTIONS AVAILABLE



FUNCTION	$\overline{OE}$	A	B	C	D
3-state inverter	L	Input	X	L	H
		X	Input	H	H
		L	H	Input	H
		H	L	Input	L
		H	X	L	Input
		X	H	H	Input
		H	H	X	Input

X = H or L

3-STATE MUX FUNCTIONS AVAILABLE



FUNCTION	$\overline{OE}$	A	B	C	D
3-state 2-to-1, data selector MUX	L	Input 1	Input 2	$\overline{\text{Input 1}}$ or Input 2	L
3-state 2-to-1, data selector MUX		Input 2	Input 1	$\overline{\text{Input 2}}$ or Input 1	L
3-state 2-to-1, data selector MUX, inverted out		Input 1	Input 2	$\overline{\text{Input 1}}$ or Input 2	H
3-state 2-to-1, data selector MUX, inverted out		Input 2	Input 1	$\overline{\text{Input 2}}$ or Input 1	H

3-STATE AND/NOR FUNCTIONS AVAILABLE

NO. OF INPUTS	AND/NAND FUNCTION	OR/NOR FUNCTION	$\overline{OE}$	A	B	C	D
2	3-state AND	3-state NOR, both inputs inverted	L	L	Input 1	Input 2	L
2	3-state AND	3-state NOR, both inputs inverted		L	Input 2	Input 1	L

NO. OF INPUTS	AND/NAND FUNCTION	OR/NOR FUNCTION	$\overline{OE}$	A	B	C	D
2	3-state AND, with A inverted	3-state NOR, with B inverted	L	Input 2	L	Input 1	L
2	3-state AND, with A inverted	3-state NOR, with B inverted		H	Input 1	Input 2	H

NO. OF INPUTS	AND/NAND FUNCTION	OR/NOR FUNCTION	$\overline{OE}$	A	B	C	D
2	3-state AND, with B inverted	3-state NOR, with A inverted	L	Input 1	L	Input 2	L
2	3-state AND, with B inverted	3-state NOR, with A inverted		H	Input 2	Input 1	H

NO. OF INPUTS	AND/NAND FUNCTION	OR/NOR FUNCTION	$\overline{OE}$	A	B	C	D
2	3-state AND, both inverted inputs	3-state NOR	L	Input 1	H	Input 2	L
2	3-state AND, both inverted inputs	3-state NOR		Input 2	H	Input 1	L

3-STATE NAND/OR FUNCTIONS AVAILABLE

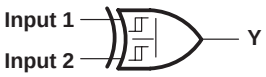
NO. OF INPUTS	AND/NAND FUNCTION	OR/NOR FUNCTION	$\overline{OE}$	A	B	C	D
2	3-state NAND	3-state OR, both inputs inverted	L	L	Input 1	Input 2	H
2	3-state NAND	3-state OR, both inputs inverted		L	Input 2	Input 1	H

NO. OF INPUTS	AND/NAND FUNCTION	OR/NOR FUNCTION	$\overline{OE}$	A	B	C	D
2	3-state NAND, with A inverted	3-state OR, with B inverted	L	Input 2	L	Input 1	H
2	3-state NAND, with A inverted	3-state OR, with B inverted		H	Input 1	Input 2	L

NO. OF INPUTS	AND/NAND FUNCTION	OR/NOR FUNCTION	$\overline{OE}$	A	B	C	D
2	3-state NAND, with B inverted	3-state OR, with A inverted	L	Input 1	L	Input 2	H
2	3-state NAND, with B inverted	3-state OR, with A inverted		H	Input 2	Input 1	L

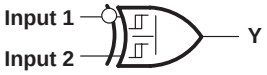
NO. OF INPUTS	AND/NAND FUNCTION	OR/NOR FUNCTION	$\overline{OE}$	A	B	C	D
2	3-state NAND, both inputs inverted	3-state OR	L	Input 1	H	Input 2	L
2	3-state NAND, both inputs inverted	3-state OR		Input 2	H	Input 1	L

3-STATE XOR/XNOR FUNCTIONS AVAILABLE

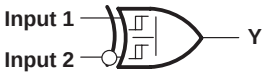


FUNCTION	$\overline{OE}$	A	B	C	D
3-state XOR	L	Input 1	X	L	Input 2
		Input 2	X	L	Input 1
		X	Input 1	H	Input 2
		X	Input 2	H	Input 1
		L	H	Input 1	Input 2
		L	H	Input 2	Input 1

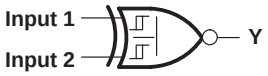
3-STATE XOR/XNOR FUNCTIONS AVAILABLE (continued)



FUNCTION	$\overline{OE}$	A	B	C	D
3-state XOR, with A inverted	L	H	L	Input 1	Input 2



FUNCTION	$\overline{OE}$	A	B	C	D
3-state XOR, with B inverted	L	H	L	Input 1	Input 2



FUNCTION	$\overline{OE}$	A	B	C	D
3-state XNOR	L	H	L	Input 1	Input 2
3-state XNOR		H	L	Input 2	Input 1

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . −0.5 V to 4.6 V
Input voltage range, V_I (see Note 1) . . . . . −0.5 V to 4.6 V
Voltage range applied to any output in the high-impedance or power-off state, V_O (see Note 1) . . . . . −0.5 V to 4.6 V
Output voltage range in the high or low state, V_O (see Note 1) . . . . . −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0) . . . . . −50 mA
Output clamp current, I_{OK} (V_O < 0) . . . . . −50 mA
Continuous output current, I_O . . . . . ±20 mA
Continuous current through V_{CC} or GND . . . . . ±50 mA
Package thermal impedance, θ_{JA} (see Note 2): DCT package . . . . . 220°C/W
DCU package . . . . . 227°C/W
YEP/YZP package . . . . . 102°C/W
Storage temperature range, T_{stg} . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		0.8	3.6	V
V_I	Input voltage		0	3.6	V
V_O	Output voltage	Active state	0	V_{CC}	V
		3-state	0	3.6	
I_{OH}	High-level output current	V_{CC} = 0.8 V		−20	μA
		V_{CC} = 1.1 V		−1.1	mA
		V_{CC} = 1.4 V		−1.7	
		V_{CC} = 1.65		−1.9	
		V_{CC} = 2.3 V		−3.1	
		V_{CC} = 3 V		−4	
I_{OL}	Low-level output current	V_{CC} = 0.8 V		20	μA
		V_{CC} = 1.1 V		1.1	mA
		V_{CC} = 1.4 V		1.7	
		V_{CC} = 1.65 V		1.9	
		V_{CC} = 2.3 V		3.1	
		V_{CC} = 3 V		4	
$\Delta t/\Delta v$	Input transition rise or fall rate	V_{CC} = 0.8 V to 3.6 V		200	ns/V
T_A	Operating free-air temperature		−40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C		T_A = −40°C TO 85°C		UNIT
			MIN	MAX	MIN	MAX	
V_{T+} Positive-going input threshold voltage		0.8 V	0.3	0.6	0.3	0.6	V
		1.1 V	0.53	0.9	0.53	0.9	
		1.4 V	0.74	1.11	0.74	1.11	
		1.65 V	0.91	1.29	0.91	1.29	
		2.3 V	1.37	1.77	1.37	1.77	
		3 V	1.88	2.29	1.88	2.29	
V_{T-} Negative-going input threshold voltage		0.8 V	0.1	0.6	0.1	0.6	V
		1.1 V	0.26	0.65	0.26	0.65	
		1.4 V	0.39	0.75	0.39	0.75	
		1.65 V	0.47	0.84	0.47	0.84	
		2.3 V	0.69	1.04	0.69	1.04	
		3 V	0.88	1.24	0.88	1.24	
ΔV_T Hysteresis ($V_{T+} - V_{T-}$)		0.8 V	0.07	0.5	0.07	0.5	V
		1.1 V	0.08	0.46	0.08	0.46	
		1.4 V	0.18	0.56	0.18	0.56	
		1.65 V	0.27	0.66	0.27	0.66	
		2.3 V	0.53	0.92	0.53	0.92	
		3 V	0.79	1.31	0.79	1.31	
V_{OH}	I_{OH} = −20 μA	0.8 V to 3.6 V	V_{CC} − 0.1		V_{CC} − 0.1		V
	I_{OH} = −1.1 mA	1.1 V	0.75 × V_{CC}		0.7×V_{CC}		
	I_{OH} = −1.7 mA	1.4 V	1.11		1.03		
	I_{OH} = −1.9 mA	1.65 V	1.32		1.3		
	I_{OH} = −2.3 mA	2.3 V	2.05		1.97		
	I_{OH} = −3.1 mA		1.9		1.85		
	I_{OH} = −2.7 mA	3 V	2.72		2.67		
	I_{OH} = −4 mA		2.6		2.55		
V_{OL}	I_{OL} = 20 μA	0.8 V to 3.6 V		0.1		0.1	V
	I_{OL} = 1.1 mA	1.1 V		0.3×V_{CC}		0.3×V_{CC}	
	I_{OL} = 1.7 mA	1.4 V		0.31		0.37	
	I_{OL} = 1.9 mA	1.65 V		0.31		0.35	
	I_{OL} = 2.3 mA	2.3 V		0.31		0.33	
	I_{OL} = 3.1 mA			0.44		0.45	
	I_{OL} = 2.7 mA	3 V		0.31		0.33	
	I_{OL} = 4 mA			0.44		0.45	
I_I All inputs	V_I = GND to 3.6 V	0 V to 3.6 V		0.1		0.5	μA
I_{off}	V_I or V_O = 0 V to 3.6 V	0 V		0.2		0.6	μA
ΔI_{off}	V_I or V_O = 0 V to 3.6 V	0 V to 0.2 V		0.2		0.6	μA
I_{OZ}	V_O = V_{CC} or GND	3.6 V		0.1		0.5	μA

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			T_A = −40°C TO 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
I_{CC}		V_I = GND or (V_{CC} to 3.6 V), $\overline{OE}$ = GND, I_O = 0	0.8 V to 3.6 V			0.5		0.9	µA
ΔI_{CC}	Data inputs	V_I = V_{CC} − 0.6 V,† I_O = 0	3.3 V			40		50	µA
	$\overline{OE}$ input				110			120	
	All inputs	V_I = GND to 3.6 V, $\overline{OE}$ = V_{CC}‡	0.8 V to 3.6 V		0				nA
C_i		V_I = V_{CC} or GND	0 V		1.5				pF
			3.6 V		1.5				
C_o		V_O = V_{CC} or GND	3.6 V		3				pF

† One input at V_{CC} − 0.6 V, other input at V_{CC} or GND
‡ To show I_{CC} is very low when the input-disable feature is enabled.

switching characteristics over recommended operating free-air temperature range, C_L = 5 pF (unless otherwise noted) (see Figures 3 and 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C			T_A = −40°C TO 85 °C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A, B, C, or D	Y	0.8 V		32				ns
			1.2 V ± 0.1 V	0.5	9.9	20.1	0.5	26.6	
			1.5 V ± 0.1 V	1.4	6.6	11.9	0.5	16.8	
			1.8 V ± 0.15 V	1.8	5.3	8.9	1	13	
			2.5 V ± 0.2 V	2.1	3.9	5.8	1.3	8.9	
			3.3 V ± 0.3 V	1.9	3.3	4.8	1.2	7.4	
t_{en}	$\overline{OE}$	Y	0.8 V		35				ns
			1.2 V ± 0.1 V	0.6	11.1	21.7	0.5	25.2	
			1.5 V ± 0.1 V	2.3	7.4	12.6	1.4	16.4	
			1.8 V ± 0.15 V	2	5.7	9.4	1.1	12.8	
			2.5 V ± 0.2 V	2.1	4.1	6.2	1.2	8.5	
			3.3 V ± 0.3 V	1.9	3.4	5	1.1	6.7	
t_{dis}	$\overline{OE}$	Y	0.8 V		9.8				ns
			1.2 V ± 0.1 V	1.4	4.5	7.7	1.5	8.2	
			1.5 V ± 0.1 V	1.7	3.2	4.8	1.7	6	
			1.8 V ± 0.15 V	1.5	3	4.7	1.3	6.1	
			2.5 V ± 0.2 V	0.9	1.9	3	0.7	4.2	
			3.3 V ± 0.3 V	0.8	2.5	4.4	0.7	4.5	

switching characteristics over recommended operating free-air temperature range, C_L = 10 pF (unless otherwise noted) (see Figures 3 and 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C			T_A = −40°C TO 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A, B, C, or D	Y	0.8 V		36				ns
			1.2 V ± 0.1 V	0.4	10.7	21.1	0.7	29.8	
			1.5 V ± 0.1 V	2	7.2	12.6	1.1	18.5	
			1.8 V ± 0.15 V	2.3	5.8	9.5	1.5	14.5	
			2.5 V ± 0.2 V	2.5	4.4	6.3	1.7	10.5	
			3.3 V ± 0.3 V	2.3	3.7	5.2	1.5	8.4	
t_{en}	$\overline{OE}$	Y	0.8 V		0				ns
			1.2 V ± 0.1 V	1.4	12.1	22.8	0.8	29.3	
			1.5 V ± 0.1 V	2.8	8	13.3	2	18.7	
			1.8 V ± 0.15 V	2.5	6.2	10	1.6	14.8	
			2.5 V ± 0.2 V	2.5	4.5	6.7	1.6	9.9	
			3.3 V ± 0.3 V	2.3	3.8	5.4	1.5	8.2	
t_{dis}	$\overline{OE}$	Y	0.8 V		0				ns
			1.2 V ± 0.1 V	2	5.6	9.3	2	10	
			1.5 V ± 0.1 V	2.5	4.1	5.8	2.4	7.6	
			1.8 V ± 0.15 V	2.9	4.2	5.7	2.7	7.9	
			2.5 V ± 0.2 V	1.1	2.7	4.4	1.1	5.5	
			3.3 V ± 0.3 V	1.9	3.5	5.2	1.9	5.8	

switching characteristics over recommended operating free-air temperature range, C_L = 15 pF (unless otherwise noted) (see Figures 3 and 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C			T_A = −40°C TO 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A, B, C, or D	Y	0.8 V		38				ns
			1.2 V ± 0.1 V	0.9	11.4	22	0.5	30.8	
			1.5 V ± 0.1 V	2.5	7.8	13.2	1.6	19.2	
			1.8 V ± 0.15 V	2.7	6.3	10	1.9	15.1	
			2.5 V ± 0.2 V	2.8	4.7	6.6	2	10.8	
			3.3 V ± 0.3 V	2.6	4	5.5	1.8	8.8	
t_{en}	$\overline{OE}$	Y	0.8 V		44				ns
			1.2 V ± 0.1 V	1.8	13	24.2	1.3	30.6	
			1.5 V ± 0.1 V	3.2	8.6	14.1	2.4	19.5	
			1.8 V ± 0.15 V	2.9	6.7	10.6	2	15.4	
			2.5 V ± 0.2 V	2.8	4.9	7	1.9	10.3	
			3.3 V ± 0.3 V	2.6	4.1	5.7	1.8	8.6	
t_{dis}	$\overline{OE}$	Y	0.8 V		13				ns
			1.2 V ± 0.1 V	2.7	6.3	9.9	2.8	10.7	
			1.5 V ± 0.1 V	3.2	4.6	6.1	3.1	8	
			1.8 V ± 0.15 V	3.2	4.8	6.6	3	8.8	
			2.5 V ± 0.2 V	2.2	3.4	4.7	2	6	
			3.3 V ± 0.3 V	2.4	4.4	6.5	2.3	7.2	

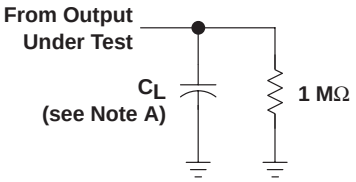
switching characteristics over recommended operating free-air temperature range, C_L = 30 pF (unless otherwise noted) (see Figures 3 and 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C			T_A = −40°C TO 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A, B, C, or D	Y	0.8 V		48				ns
			1.2 V ± 0.1 V	3.1	14	24.9	2.6	36.1	
			1.5 V ± 0.1 V	4.2	9.6	15.1	3.3	23.1	
			1.8 V ± 0.15 V	4.1	7.9	11.7	3.3	18	
			2.5 V ± 0.2 V	4.1	5.9	7.9	3.1	12.7	
			3.3 V ± 0.3 V	3.7	5.1	6.7	2.8	10.4	
t_{en}	$\overline{OE}$	Y	0.8 V		50				ns
			1.2 V ± 0.1 V	4.4	16	27.6	3.9	36.8	
			1.5 V ± 0.1 V	5.3	10.7	16.2	4.3	23.6	
			1.8 V ± 0.15 V	4.6	8.5	12.4	3.6	18.6	
			2.5 V ± 0.2 V	4.2	6.3	8.5	3.2	12.6	
			3.3 V ± 0.3 V	3.8	5.4	7.1	2.9	10.2	
t_{dis}	$\overline{OE}$	Y	0.8 V		19				ns
			1.2 V ± 0.1 V	6	10.1	14.2	6	14.6	
			1.5 V ± 0.1 V	5.1	7.4	10.6	5	10.1	
			1.8 V ± 0.15 V	5.5	8.6	11.6	5.5	12.1	
			2.5 V ± 0.2 V	3.3	5.9	8.3	3.3	8.9	
			3.3 V ± 0.3 V	6	8.7	10.9	5.9	11.8	

operating characteristics, T_A = 25°C

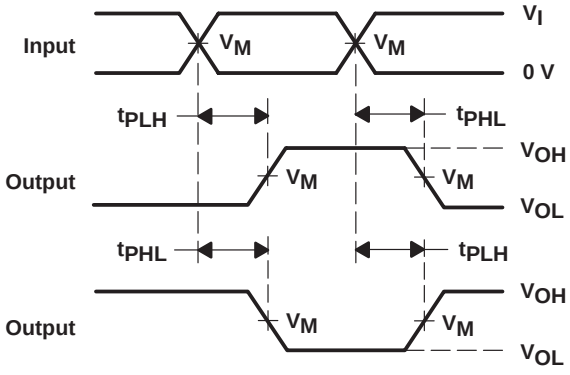
PARAMETER			TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	Outputs enabled	f = 10 MHz	0.8 V	4	pF
				1.2 V ± 0.1 V	4	
				1.5 V ± 0.1 V	4	
				1.8 V ± 0.15 V	4	
				2.5 V ± 0.2 V	5	
				3.3 V ± 0.3 V	5	
		Outputs disabled		0.8 V	0	
				1.2 V ± 0.1 V	0	
				1.5 V ± 0.1 V	0	
				1.8 V ± 0.15 V	0	
				2.5 V ± 0.2 V	0	
				3.3 V ± 0.3 V	0	

PARAMETER MEASUREMENT INFORMATION
(Propagation Delays, Setup and Hold Times, and Pulse Width)

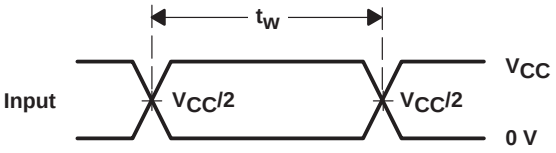


LOAD CIRCUIT

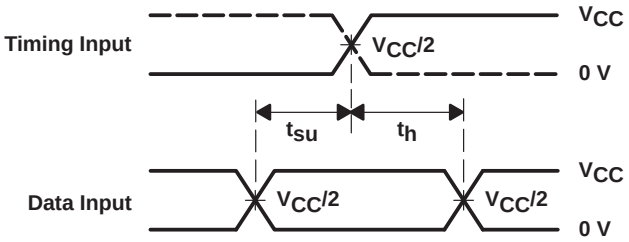
	V_{CC} = 0.8 V	V_{CC} = 1.2 V ± 0.1 V	V_{CC} = 1.5 V ± 0.1 V	V_{CC} = 1.8 V ± 0.15 V	V_{CC} = 2.5 V ± 0.2 V	V_{CC} = 3.3 V ± 0.3 V
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
PULSE DURATION

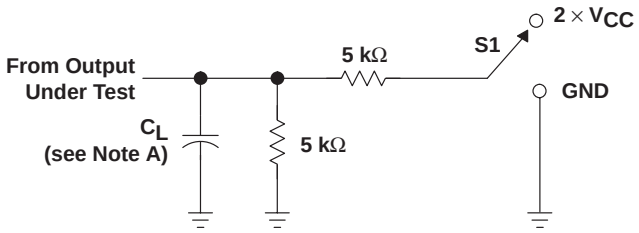


VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, for propagation delays t_r/t_f = 3 ns, for setup and hold times and pulse width t_r/t_f = 1.2 ns.
C. The outputs are measured one at a time, with one transition per measurement.
D. t_{PLH} and t_{PHL} are the same as t_{pd}.
E. All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms

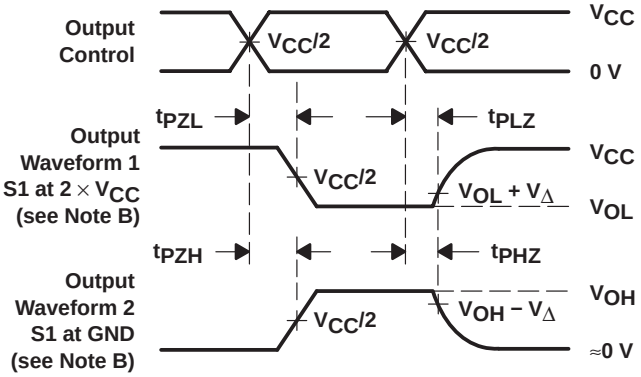
PARAMETER MEASUREMENT INFORMATION
(Enable and Disable Times)



LOAD CIRCUIT

TEST	S1
t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	$2 \times V_{CC}$ GND

	V_{CC} = 0.8 V	V_{CC} = 1.2 V ± 0.1 V	V_{CC} = 1.5 V ± 0.1 V	V_{CC} = 1.8 V ± 0.15 V	V_{CC} = 2.5 V ± 0.2 V	V_{CC} = 3.3 V ± 0.3 V
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}
V_Δ	0.1 V	0.1 V	0.1 V	0.15 V	0.15 V	0.3 V



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r/t_f = 3 ns.
D. The outputs are measured one at a time, with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. All parameters and waveforms are not applicable to all devices.

Figure 4. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
SN74AUP1G99DCTR	ACTIVE	SM8	DCT	8	3000	None	CU SNPB	Level-1-235C-UNLIM
SN74AUP1G99DCTT	ACTIVE	SM8	DCT	8	250	None	CU SNPB	Level-1-235C-UNLIM
SN74AUP1G99DCUR	ACTIVE	US8	DCU	8	3000	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G99DCUT	ACTIVE	US8	DCU	8	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM

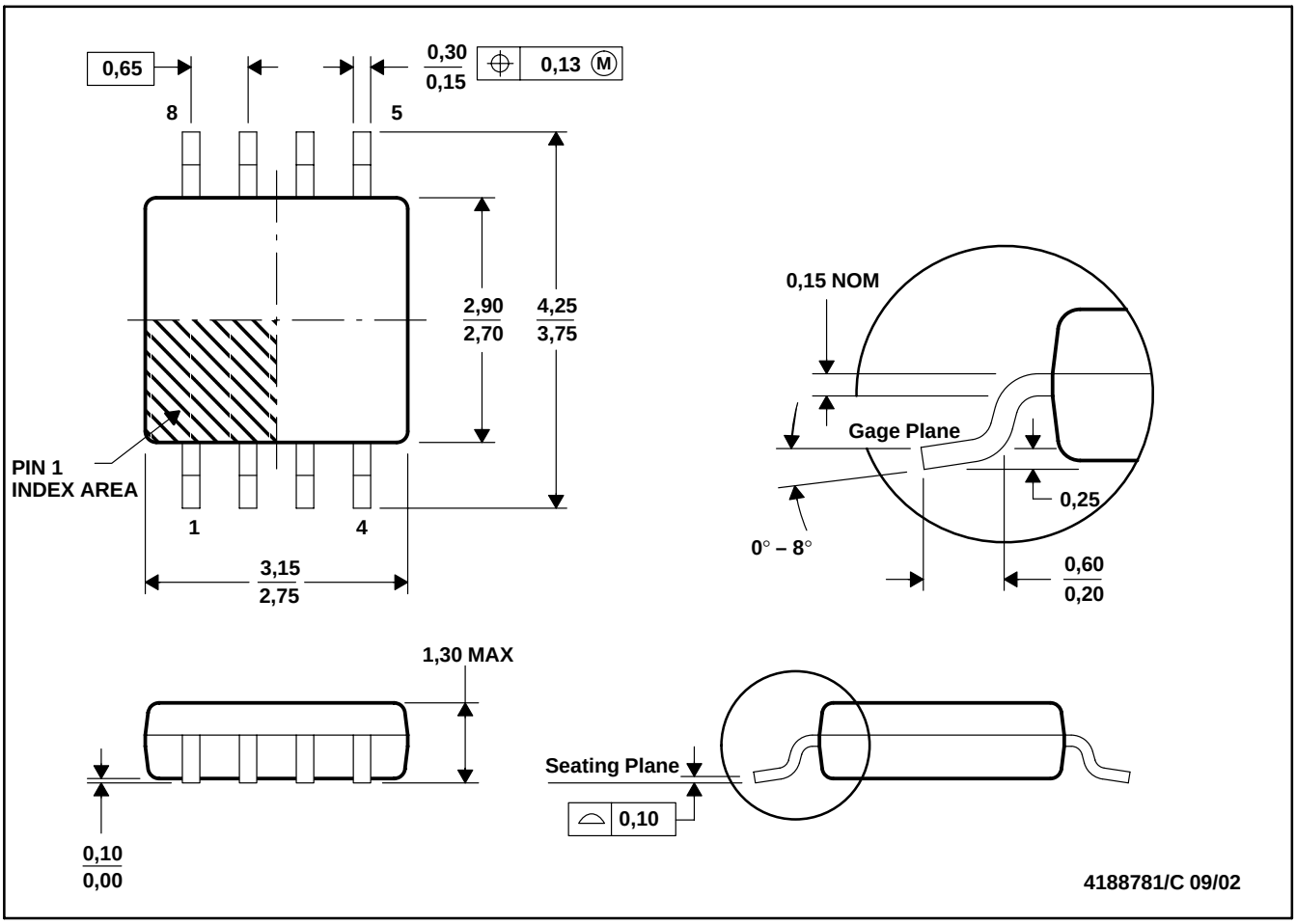
(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
None: Not yet available Lead (Pb-Free).
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

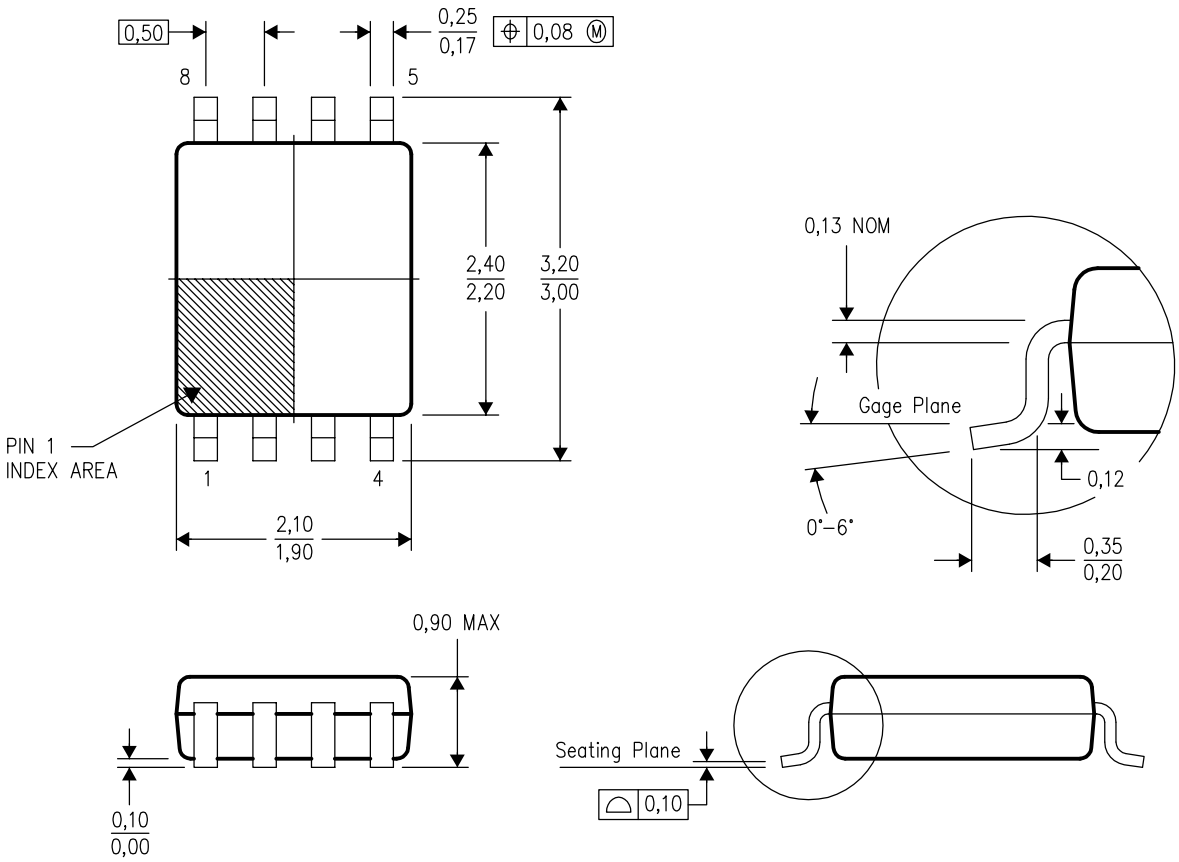
MPDS049B – MAY 1999 – REVISED OCTOBER 2002

DCT (R-PDSO-G8) **PLASTIC SMALL-OUTLINE PACKAGE**



NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion
D. Falls within JEDEC MO-187 variation DA.

DCU (R–PDSO–G8) PLASTIC SMALL–OUTLINE PACKAGE (DIE DOWN)



4200503/E 05/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion.
D. Falls within JEDEC MO–187 variation CA.

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